

3D Direct Laser Writing is a tool to fabricate 3D freeform structures down sub  $\mu\text{m}$ . It is based on *Two-Photon Lithography* but beyond that 2D and 2.5D structures with nano dimensions are also possible. This system uses a nonlinear two-photon absorption process to modify, *e.g.* polymerize, a photosensitive medium at a specific point in the resist. By scanning the photoresist with a stage over this point a 3D-structure with dimensions in the submicron scale or greater can be written.

## Contact

See KNMF website or contact the KNMF User Office.

## Equipment

- Nanoscribe Photonic Professional GT
  - Several sample holders
  - Galvoscan unit
  - Hybrid stage for large accurate travel distances
- Critical point dryer (supercritical  $\text{CO}_2$ )
- Coming soon: UV flood exposure (shell writing mode for large structures)

## Features

- Resolution:
  - 3D: 200 nm lateral, 750 nm normal
  - 2D: 180 nm
- Feature Structure size: max.  $600 \times 600 \times 3700 \mu\text{m}^3$  depending on filling factor
- Writing modes:
  - piezo (100x DIP), galvoscan (63x GT, 25x GT)
- Corresponding writing fields:  $300 \times 300 \times 300 \mu\text{m}^3$ ;  $140 \times 140 \mu\text{m}^2$ ;  $280 \times 280 \mu\text{m}^2$
- Writing times: piezo slow, galvoscan fast
- Larger areas have to be stitched
- Accessible writing area:  $100 \times 100 \text{mm}^2$  where structures could be placed

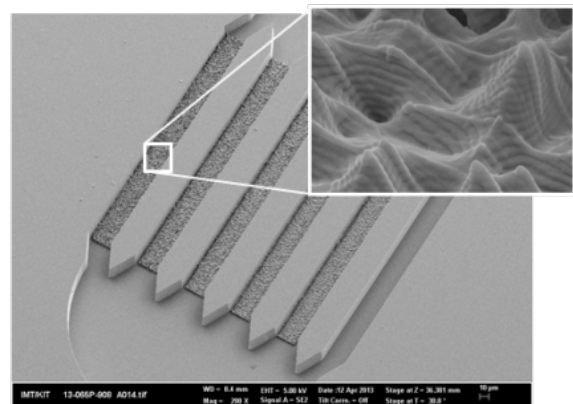
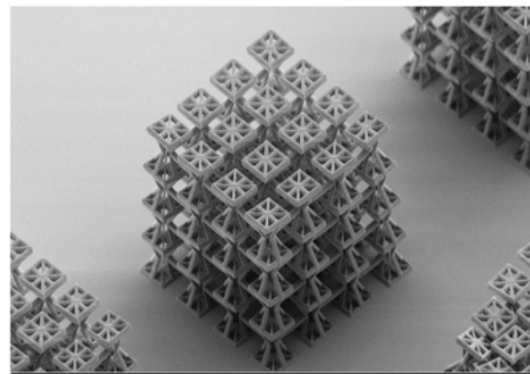
## Limitations/constraints

- The realizable structure size depends on the structural stability of the design
- The best results can be reached by using the IP-resists

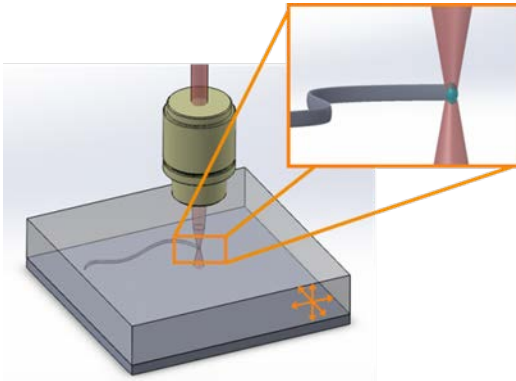
## Materials

- Negative / positive / experimental resists  
*Details and substrates see next page*

## Sample structures



## Writing principle



Sketch of the writing of a line in 3D-space inside a resist layer. The inset shows the modification in the voxel (blue) at the focal position. Only in the voxel two-photon absorption occurs.

## Writing modes



Oil

- structure height
- Fixed thin substrate
- any resist usable



Air

- Higher AR of voxel
- Bigger voxel
- Bigger processing effort
- Only solid resist
- no transparent substrate needed
- High working distance



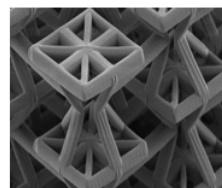
DiLL

- Not every resist usable
- Special glass substrates
- Small working distance
- structure height
- Very small voxel



GT

- Special glass substrates
- no vertical lines possible
- 100x faster than other writing modes



## Resists

- Negative Resists: IP-L, IP-G, IP-Dip, IP-S, and similar resists that are photosensitive at a wavelength of 380nm
- Positive Resist: AZ9260 (in preparation)
- Experimental Resists are possible, but only the Air mode objective or oil-immersion Objective are applied. Dip-in techniques can only be used with proven compatibility.

## 3D Direct Laser Writing



### Substrates

- 25 x 25 x 0.7 mm Glass, glass covered with ITO, cover slides 22 x 22 x 0.17 mm
- Si-wafer 4'' (100 mm)
- Si/SiO<sub>2</sub>-wafer 4'' (100 mm)
- Metallized Si-Wafer (Cr/Au)
- Other substrates have to be provided by the user.

### Data

- Stl-format
- CAD data can be exported in stl-format:
- Sometimes CAD programs export erroneous stl-files. Solid works and similar programs used in mechanical engineering produce correct stl.files.
- To avoid errors within stl-files the following rules can help:
  - Use correct units during construction ( $\mu\text{m}$ ), otherwise resolution could be bad
  - Use volumes, no areas, these objects have to be closed
  - Avoid Boolean operations
  - Avoid duplexes (use snaps)
  - Think about plane orientation. Normals are used to define interior or exterior. Therefore construct plane consistently.
  - Avoid additional structures not necessary (not written) to your part. Correction of the stl-file is nearly impossible
  - In case of periodic structures a single unit cell is sufficient.